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(54) **MULTILAYER FILM SUBSTRATE, ACOUSTIC WAVE DEVICE, MODULE, AND METHOD FOR PRODUCING MULTILAYER FILM SUBSTRATE**

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(57) **ABSTRACT**

A multilayer film substrate includes a piezoelectric substrate, a first insulating film formed on the piezoelectric substrate, a support substrate, a second insulating film formed on the support substrate, and a bonding layer formed between the first insulating film and the second insulating film. The piezoelectric substrate and the support substrate are bonded each other using the first insulating film, the second insulating film, and the bonding layer as an inter-layer.

